CLAIMS

What is claimed is:

1.   In a method of bonding a heat sink or similar member to a dielectric material of an electronic package wherein said dielectric material has a surface having a quantity of silicone thereon and bonding said heat sink or similar member to said surface is accomplished by applying an adhesive to said surface and/or said heat sink, the improvement comprising roughening said surface of said dielectric material prior to applying said adhesive to said surface and/or said heat sink.

2.   The method of claim 1 wherein said roughening of said surface of said dielectric material is accomplished by rubbing an abrasive member on said surface.

3.   The method of claim 1 wherein said abrasive member is rubbed on said surface for a total of about 5 to about 10 strokes.

4.   The method of claim 1 further including substantially curing said adhesive for a predetermined time period at a predetermined temperature.

5.   The method of claim 4 wherein said predetermined temperature is room temperature.

6.   The method of claim 5 wherein said time period is from about five minutes to about twelve hours.

7.   The method of claim 1 further including exposing said surface of said dielectric material to a plasma prior to said applying of said adhesive.

8. The method of claim 7 wherein said plasma is maintained at a pre-established pressure with a predetermined flow rate for an established time period.

9. The method of claim 8 wherein said pre-established pressure is about 0.35 torr, said predetermined flow rate is about 75 standard cubic centimeters/minute and said established time period is about 3 minutes.

10. The method of claim 9 wherein about 300 watts of power are generated during said exposing said surface of said dielectric material to said plasma.

11. The method of claim 1 further including electriclaly coupling said electronic package to a host substrate, said coupling occurring prior to bonding said heat sink or similar member to said dielectric material.

12. A method of marking a dielectric material of an electronic package wherein said dielectric material has a surface with a quantity of silicone thereon and said marking involves the deposition of a predetermined pattern of ink onto said surface, the improvement comprising roughening said surface of said dielectric material prior to said deposition of said predetermined pattern of ink.

13. The method of claim 12 wherein said roughening of said surface of said dielectric material is accomplished by rubbing an abrasive member on said surface.

14. The method of claim 12 wherein said abrasive member is rubbed on said surface for a total of about 5 to about 10 strokes.

15. The method of claim 12 further including exposing said surface of said dielectric material to a plasma prior to said deposition of said predetermined pattern of ink.

1   16.   The method of claim 15 wherein said plasma is maintained at a pre-established pressure

2   with a predetermined flow rate for an established time period.

1   17.   The method of claim 16 wherein said pre-established pressure is about 0.35 torr, said

2   predetermined flow rate is about 75 standard cubic centimeters/minute and said

3   established time period is about 3 minutes.

1   18.   The method of claim 17 wherein about 300 watts of power are generated during said

2   exposing said surface of said dielectric material to said plasma.

1   19.   An electronic package comprising:

2   a substrate;

3   a semiconductor chip positioned on and electrically coupled to said substrate;

4   an overmold substantially covering said semiconductor chip, said overmold including a

5   roughened upper surface having a quantity of silicone thereon;

6   a quantity of adhesive positioned on said roughened upper surface; and

7   a heat sink secured to said roughened upper surface by said quantity of adhesive.

1   20.   The electronic package of claim 19 wherein said overmold is comprised of polymer

2   material.

1   21.   The invention of claim 19 wherein said electronic package is a plastic ball grid array

2   package.